

POWER MANAGEMENT

Description

The SC1408 is a low voltage boost controller that operates from a 1.8V to 16.5V input range. The SC1408 was designed for two cell Alkaline or single cell Lithium Ion battery applications. With the proper external components it can be used as a boost converter or a buck/boost converter. A Shutdown pin allows the user to turn the controller off, reducing supply current to less than 2 μ A typical. Output voltage can be preset to 5V or is adjustable from 3V to 16.5V with a resistor divider. The controller changes frequency in light load conditions to improve efficiency.

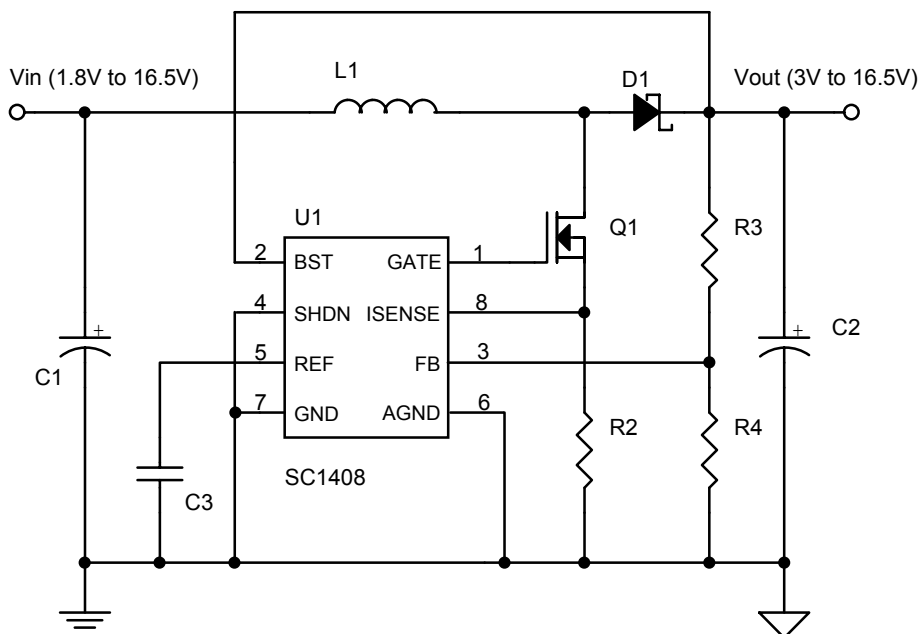
Features

- ◆ 1.8V to 16.5V input range
- ◆ Preset (5V) or adjustable output
- ◆ Ground referenced current limit
- ◆ On chip precision reference
- ◆ Up to 300kHz switching frequency
- ◆ 10 μ A max shutdown current
- ◆ Industrial temperature range
- ◆ SO-8 and MSOP-8 packages. Lead free packages available are fully WEEE and RoHS compliant

Applications

- ◆ PDA Power supplies
- ◆ Battery powered applications
- ◆ Positive LCD Bias generator
- ◆ Portable communications (cellular phones)
- ◆ Peripheral card supplies
- ◆ Industrial power supplies

Typical Application Circuit



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Absolute Maximum Ratings

Exceeding the specifications below may result in permanent damage to the device, or device malfunction. Operation outside of the parameters specified in the Electrical Characteristics section is not implied. Exposure to Absolute Maximum rated conditions for extended periods of time may affect device reliability.

Parameter	Symbol	Maximum	Units
Input Voltage	BST to GND	-0.3 to 18	V
Small Signal Ground to Power Ground	GND to AGND	+0.1	V
GATE to GND		-0.3 to VBST +0.3 or 5	V
FB, SHDN, REF, ISENSE to GND		-0.3 to min. of VBST +0.3 or 5	V
Operating Temperature	T_A	-40 to +85	°C
Junction Temperature Range	T_J	-40 to +150	°C
Storage Temperature Range	T_{STG}	-65 to +160	°C
Lead Temperature (Soldering) 10 Sec.	T_L	+300	°C
Thermal Resistance, Junction to Ambient SO-8 MSOP-8	θ_{JA}	128 216	°C/W
Thermal Resistance, Junction to Case SO-8 MSOP-8	θ_{JC}	50 70	°C/W

Electrical Characteristics

Unless specified: $V_{OUT} = 5V$; $I_{LOAD} = 0mA$; $T_A = +25^\circ C$

Parameter	Sym	Conditions	Min	Typ	Max	Units
Input Voltage	V_{IN}	$T_A = 25^\circ C$	1.8		16.5	V
		$T_A = -40^\circ C$ to $+85^\circ C$	1.8		16.5	V
Supply Current		$V_{OUT} = 16.5V$, SHDN < 0.4V $T_A = -40^\circ C$ to $+85^\circ C$		110	140	μA
		$V_{OUT} = 10V$, $1.6V < SHDN < 5V$ $T_A = -40^\circ C$ to $+85^\circ C$		2	10	
Output Voltage	V_{OUT}	$V_{IN} = 2.0V$ to $5.0V$ $T_A = -40^\circ C$ to $+85^\circ C$	4,800	5.0	5.200	V
Load Regulation		$V_{IN} = 2.0V$, $V_{OUT} = 5V$, $I_{LOAD} = 0mA$ to $500mA$		60		mV/A
Line Regulation		$V_{IN} = 2.7V$ to $4.0V$, $V_{OUT} = 5V$, $I_{LOAD} = 500mA$		7		mV/V
Minimum Start Up Voltage		No load			1.8	V
Minimum Switch On Time	$t_{ON(Max)}$		9.6	16	22.4	μs
Minimum Switch Off Time	$t_{OFF(Min)}$		1.4	2.3	3.2	μs
Efficiency		$V_{IN} = 4V$, $V_{OUT} = 5V$, $I_{LOAD} = 0mA$ to $500mA$		87		%
Reference Voltage	V_{REF}	$I_{REF} = 0\mu A$ $T_A = -40^\circ C$ to $+85^\circ C$	1.176	1.200	1.224	V
Reference Load Regulation		$0\mu A < I_{REF} < 100\mu A$		-4	10	mV
Reference Line Regulation		$5V < V_{OUT} < 16.5V$		40	100	$\mu V/V$

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Electrical Characteristics (Cont.)

Unless specified: $V_{OUT} = 5V$; $I_{LOAD} = 0mA$; $T_A = +25^{\circ}C$

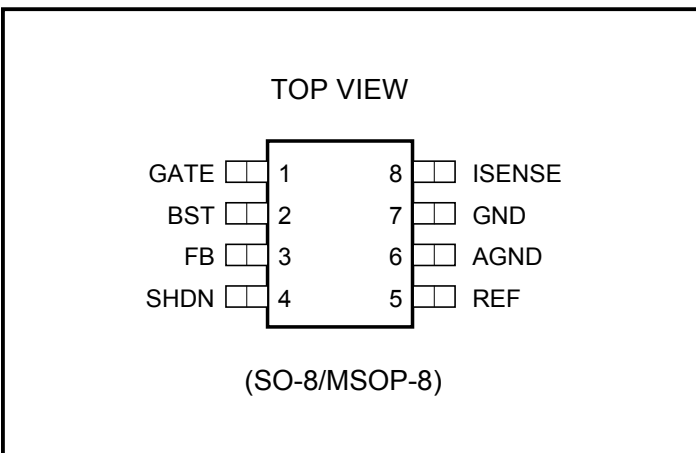
Parameter	Sym	Conditions		Min	Typ	Max	Units
FB Trip Point Voltage	V_{FB}	$T_A = 25^{\circ}C$ $T_A = -40^{\circ}C$ to $+85^{\circ}C$		1.176	1.200	1.224	V
FB Input Current	I_{FM}	$T_A = 25^{\circ}C$ $T_A = -40^{\circ}C$ to $+85^{\circ}C$			-4	± 40	nA
SHDN Input High Voltage	V_{IN}	$V_{OUT} = 2.7V$ to $16.5V$		1.6			V
SHDN Input Low Voltage	V_{IL}	$V_{OUT} = 2.7V$ to $16.5V$				0.4	V
SHDN Input Current		$V_{OUT} = 16.5V$, SHDN = 0V or 5V				± 1	μA
Current Limit Trip Level	V_{CS}	$V_{OUT} = 3V$ to $16.5V$	$T_A = 25^{\circ}C$ $T_A = -40^{\circ}C$ to $+85^{\circ}C$	85 80	100	115 120	mV
ISENSE Input Current					0.01	± 1	μA
GATE Rise Time		$V_{OUT} = 5V$, InF from GATE to GND			50		ns
GATE Fall Time		$V_{OUT} = 5V$, InF from GATE to GND			50		
GATE On Resistance		GATE = high or low			15	30	Ω

NOTE:

(1) This device is ESD sensitive. Use of standard ESD handling precautions is required.

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Pin Configuration



Ordering Information

Part Number	Package ⁽¹⁾	Temp Range (T _A)
SC1408IS.TR	SO-8	-40° to +85°C
SC1408ISTR ⁽²⁾		
SC1408IMS.TR	MSOP-8 ⁽³⁾	
SC1408IMSTR ⁽²⁾		

Notes:

(1) Only available in tape and reel packaging. A reel contains 2500 devices.

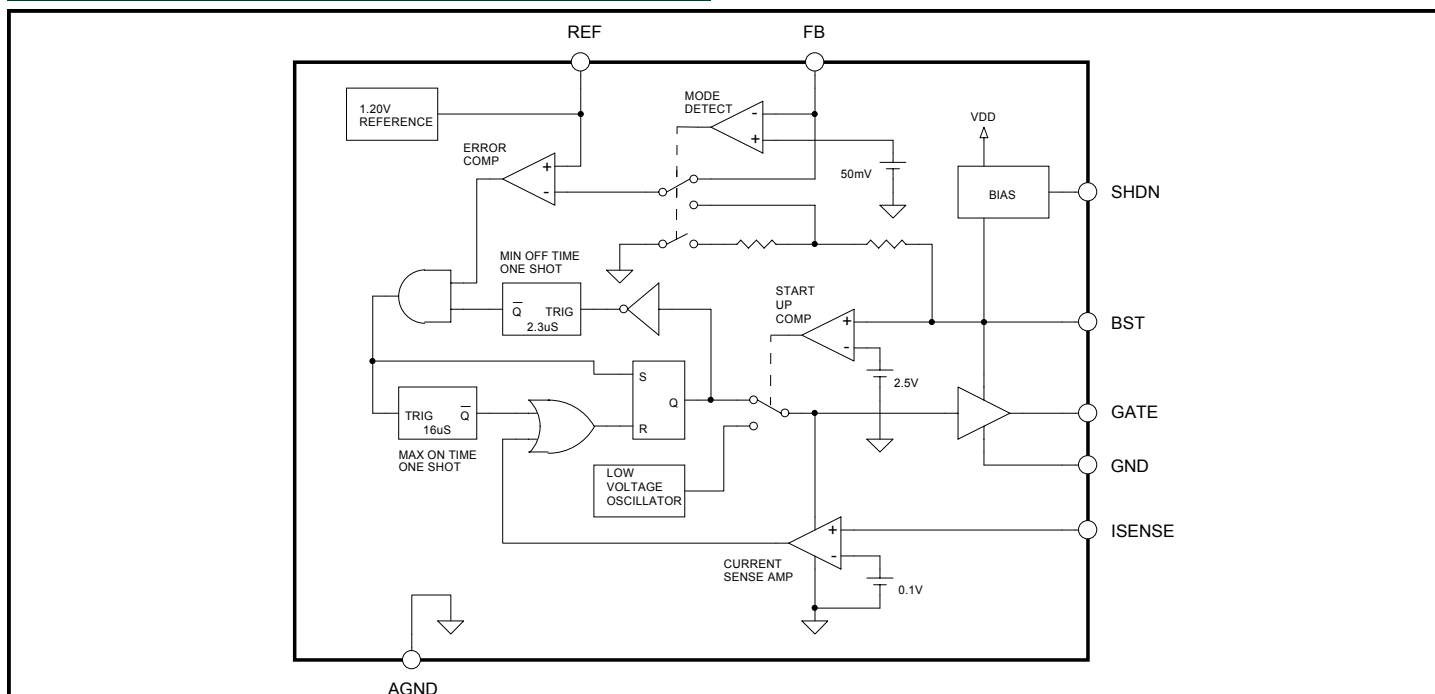
(2) Lead free product. This product is fully WEEE and RoHS compliant.

(3) Contact factory for MSOP availability

Pin Descriptions

Pin #	Pin Name	Pin Function
1	GATE	Gate drive output.
2	BST	Supply voltage.
3	FB	Voltage feedback
4	SHDN	Logic high shuts down the converter.
5	REF	Reference output pin.
6	AGND	Small signal analog and digital ground.
7	GND	Power ground.
8	ISENSE	Current sense pin.

Block Diagram



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Applications Information

Theory of Operation

The SC1408 is a modified hysteretic boost converter controller. The power switch is turned on when the output voltage falls slightly below its setpoint. It remains on for approximately 16µs, or until the inductor current reaches limit, whichever occurs first. The power switch is then turned off for 2.3 µs, or until the output voltage once again falls below setpoint, whichever occurs last.

The SC1408 is normally powered from the output voltage. Internal circuitry, such as the bandgap, comparators and one shots, will not function properly until the BST pin voltage reaches 2.5V. To ensure start-up at low input voltages, the normal control circuitry is disabled and a special, low voltage start up oscillator generates an approximate square wave at the GATE pin, initiating boost action. When the output voltage reaches 2.5V, the normal control circuitry is enabled and the start up oscillator shuts down. To conserve power, a SHDN pin is provided which, when pulled high, shuts down most internal circuitry. The output voltage will then be 1 diode drop below the input.

COMPONENT SELECTION

Boost Converter

R_{SENSE}

The value of the sense resistor is the primary determining factor for maximum output current. The SC1408 has a fixed current limit voltage threshold, which is developed by the peak inductor current flowing through R_{SENSE}. R_{SENSE} may be determined either from the maximum output current curves or from the equation below:

$$I_{O(MAX)} = \frac{V_{CS}}{R_{SENSE}} \left(1 - \frac{V_O + V_F - V_{IN}}{V_O + V_F - V_{FET}} \right) - \frac{t_{off}}{2L} \left(\frac{(V_{IN} - V_{FET})(V_O + V_F - V_{IN})}{V_O + V_F - V_{FET}} \right)$$

Where :

V_F = Output Diode Forward Voltage Drop

V_{FET} = Voltage across FET, R_{SENSE} and Inductor DCR

In the equation above, the use of 2.3µs for t_{off} may lead to slightly optimistic current values for low V_O/V_{IN} ratios. The theoretical curves use the actual value of t_{off}, V_F=0.5V, V_{FET}=0.3V and V_{CS}=0.08V and are generated for L=22µH.

Output Voltage

Output voltage can be set to 5V by connecting the FB pin to GND, or to any voltage in the 3.0V to 16.5V range using external divider resistors.

The bottom resistor in the divider chain (R4 in the typical application circuits) should be 300kΩ or less and the top resistor (R3 in the application circuits) can be calculated from

$$R3 = R4 \left(\frac{V_O}{V_{REF}} - 1 \right)$$

Inductor

The SC1408 will work with a wide range of inductor values. A good choice for most applications is 22µH. Smaller inductor values result in higher peak currents and increase output ripple, while larger values will result in slower loop response.

Transistor selection

Normally the power switch will be an N-channel MOSFET, although in certain circumstances an NPN bipolar may be substituted.

The choice of FET can be critical, especially in battery powered applications where the converter must be able to use all of the available energy in the battery. This requires that the converter be capable of starting up from very low input voltages. For example a two cell alkaline system's terminal voltage will drop to 1.8V as it approaches full discharge. For these demanding applications, a FET with low V_{GS(th)} is required. A good rule of thumb is that V_{GS(th)} should be at least 0.5V less than the minimum input voltage.

Diode

For most applications, a Schottky diode should be used as the output rectifier. It will be subjected to reverse voltages of at least V_O, and average current will be somewhat less than the Inductor peak current. Industry standard 1N5817 series or an equivalent surface mount part would be suitable.

Output Capacitors

Output capacitors should be low ESR to minimize ripple voltage and maximize efficiency. Low ESR tantalum or OSCON capacitors should be used. Ripple voltage will be approximately:

Input Capacitors

Input capacitors on a boost converter are less critical than the output capacitors, since there are no fast current pulses drawn from the input supply. A 100µF tantalum will be adequate for most applications.

POWER MANAGEMENT**Applications Information (Cont.)****COMPONENT SELECTION****SEPIC Converter****R_{SENSE}**

Again, with the SEPIC topology, the value of the sense resistor is the primary determining factor for maximum output current. The simplest approach to select R_{SENSE} is to add V_{in} to V_o and use this value as the output voltage in the output current curves or in the equation for Boost converter.

Output Voltage

Output voltage setting works exactly the same in SEPIC topology as in Boost, including the ability to set to 5V by connecting the FB pin to GND. Care must be taken to ensure that the IC supply (pin2; BST) does not exceed its 16.5V rating. In the circuit of Fig.2: This requires maximum output voltage to be limited to 16.5V-V_{in}. Higher output voltages are possible with different IC supply strategies.

Inductor

The SEPIC topology requires a coupled inductor. Again A good choice for most applications is 22μH. Smaller inductor values result in higher peak currents and increase output ripple, while larger values will result in slower loop response.

Transistor selection

The choice of FET can be critical, especially in battery powered applications where the converter must be able to use all of the available energy in the battery. This requires that the converter be capable of starting up from very low input voltages. For example a two cell alkaline system's

terminal voltage will drop to 1.8V as it approaches full discharge. For these demanding applications, a FET with low V_{GS(th)} is required. A good rule of thumb is that V_{GS(th)} should be at least 0.5V less than the minimum input voltage.

Diode

For most applications, a Schottky diode should be used as the output rectifier. It will be subjected to reverse voltages of at least V_o + V_{in} and average current will be somewhat less than the Inductor peak current. Industry standard 1N5817 series or an equivalent surface mount part would be suitable.

Output Capacitors

Output capacitors should be low ESR to minimize ripple voltage and maximize efficiency. Low ESR tantalums, OSCONs or the newer Polymer capacitors should be used.

Input Capacitors

Input capacitors on a SEPIC converter are less critical than the output capacitors, since there are no fast current pulses drawn from the input supply. A 100μF tantalum will be adequate for most applications.

Series Capacitors

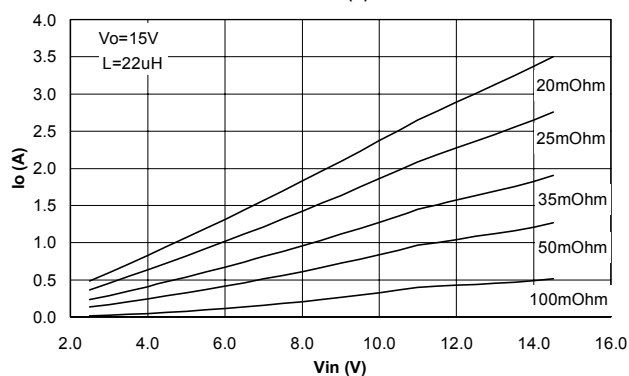
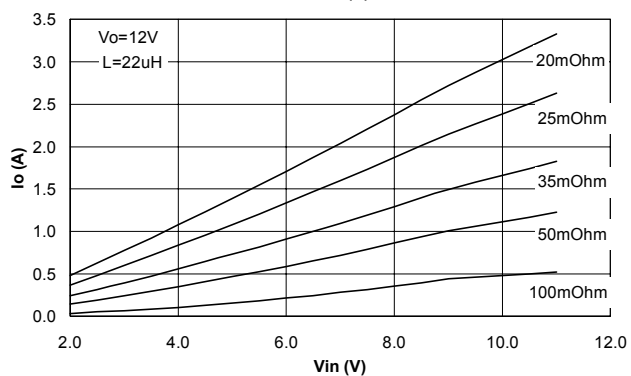
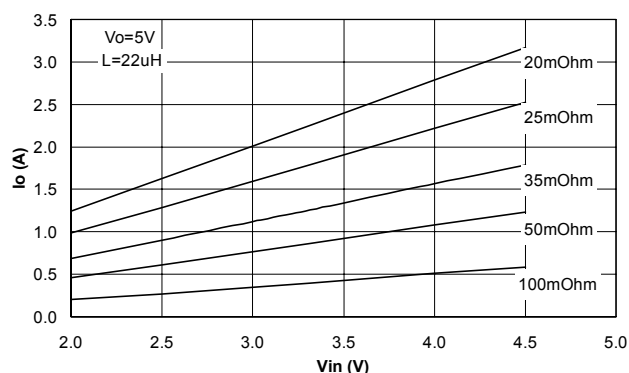
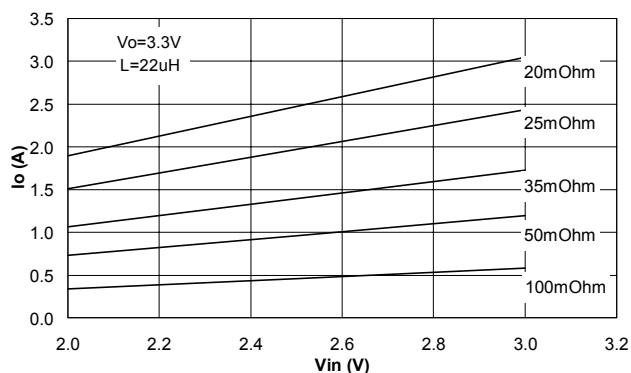
The Series capacitor(s) must be capable of handling an RMS current given by:-

$$I_{RMS} = I_o \sqrt{\frac{V_o + 0.5}{V_{IN}}}$$

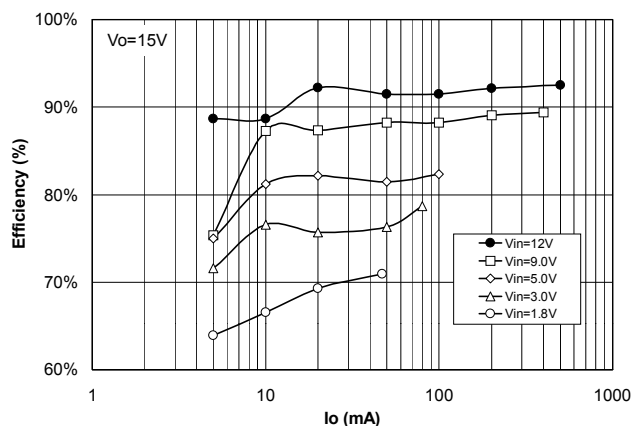
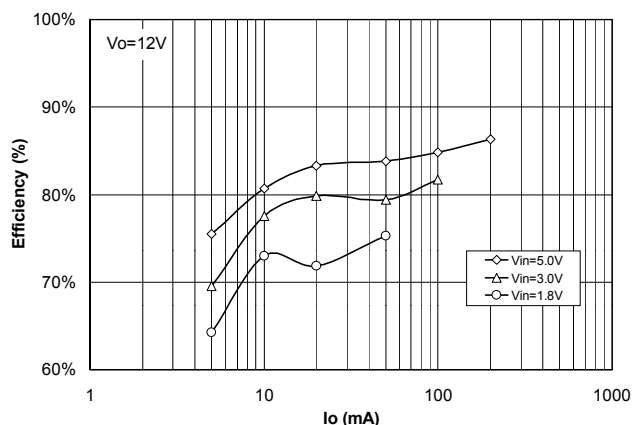
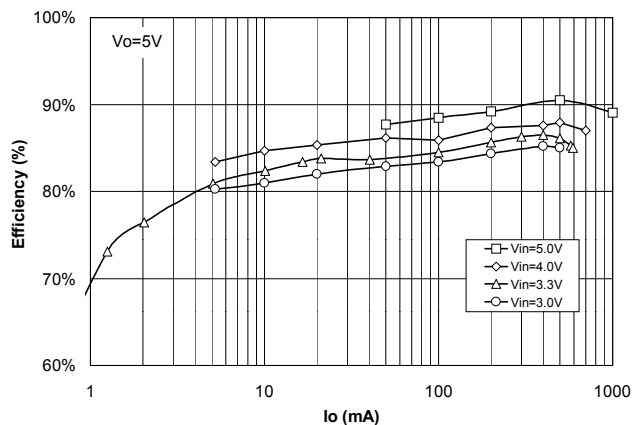
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Typical Characteristics

Figs.5 - 8: Maximum output current vs. input voltage and sense resistor value. (Boost Mode)



Figs.9-11: Efficiency in the Boost Application circuit of Fig.1



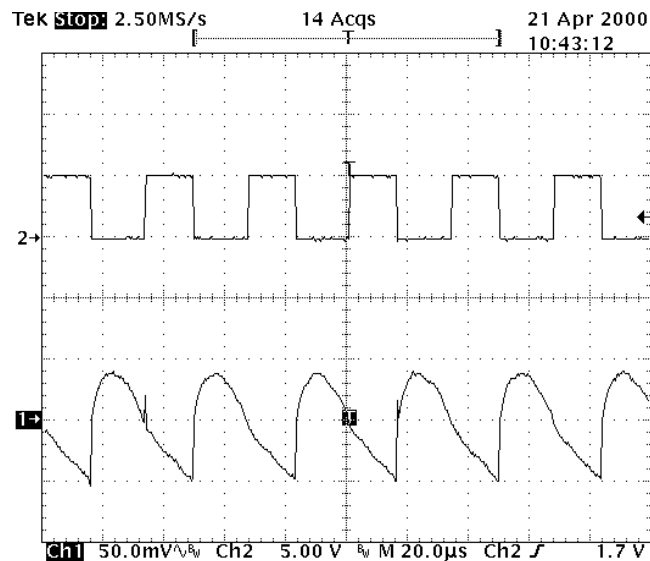
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Typical Characteristics

Output Ripple Voltage; $V_{in}=3V$, $V_o=5V$, $I_o=470mA$

Ch1 = Output Ripple

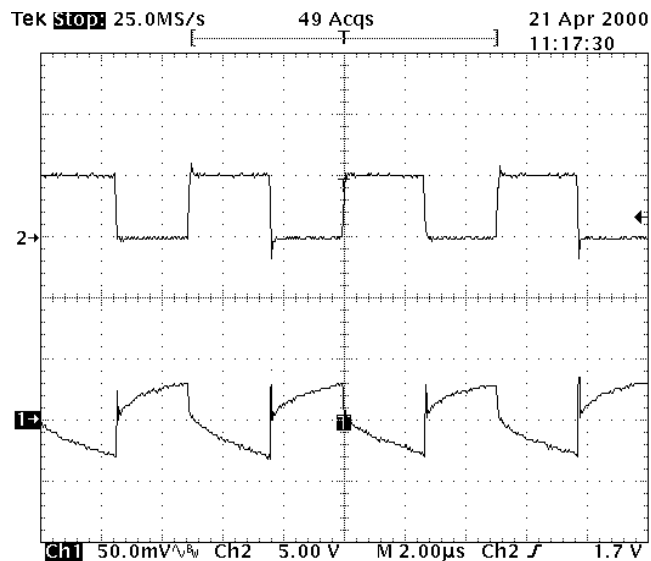
Ch2 = Voltage at GATE pin



Output Ripple Voltage; $V_{in}=3V$, $V_o=5V$, $I_o=810mA$

Ch1 = Output Ripple

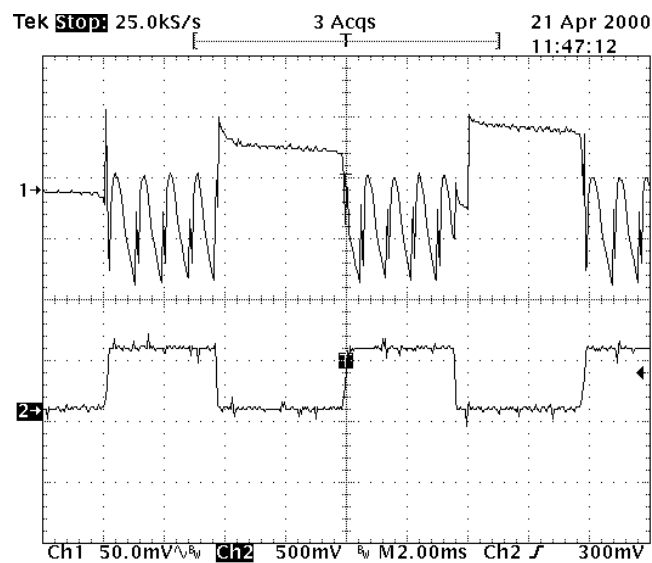
Ch2 = Voltage at GATE pin



Load Transient; $V_{in}=3V$, $V_o=5V$, $I_o=0$ to $500mA$

Ch1 = Output Voltage

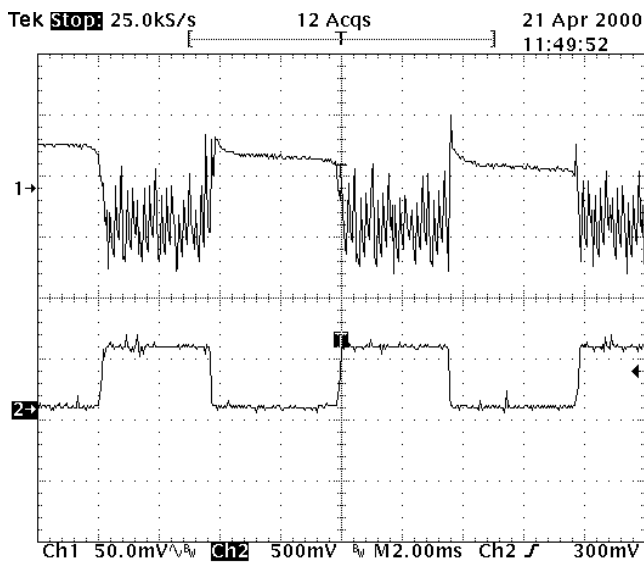
Ch2 = Load Current (0.5A/div)



Load Transient; $V_{in}=2V$, $V_o=5V$, $I_o=0$ to $500mA$

Ch1 = Output Voltage

Ch2 = Load Current (0.5A/div)



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Typical Application Circuit (Cont.)

Fig.1: Typical Application - Boost Configuration

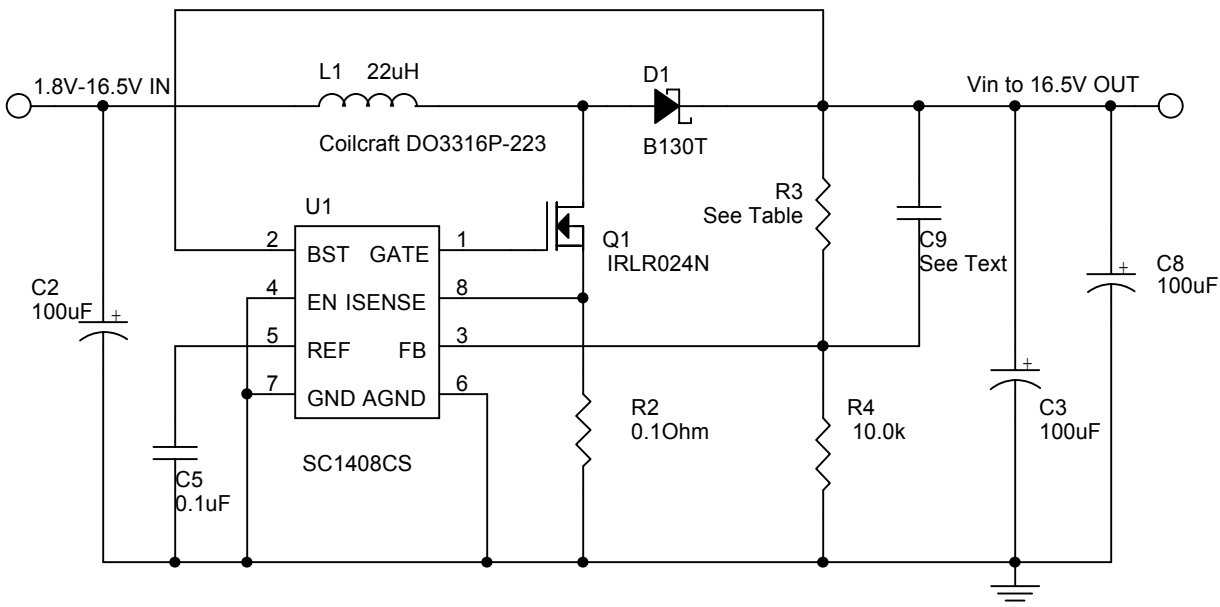
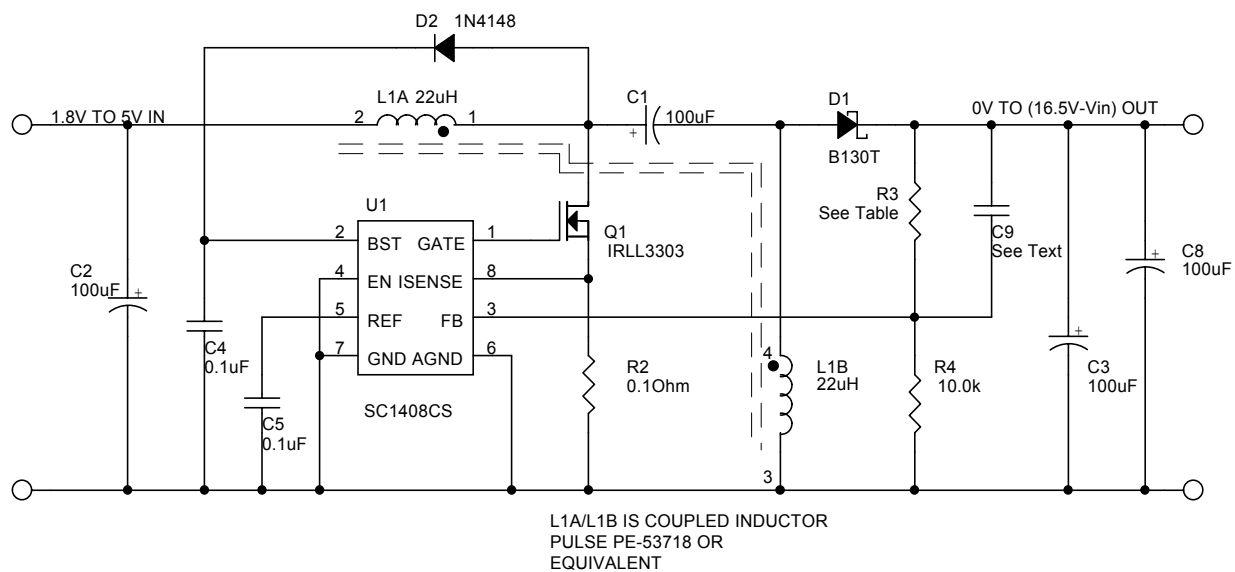


Fig.2: Typical Application - Buck/Boost (SEPIC) Configuration



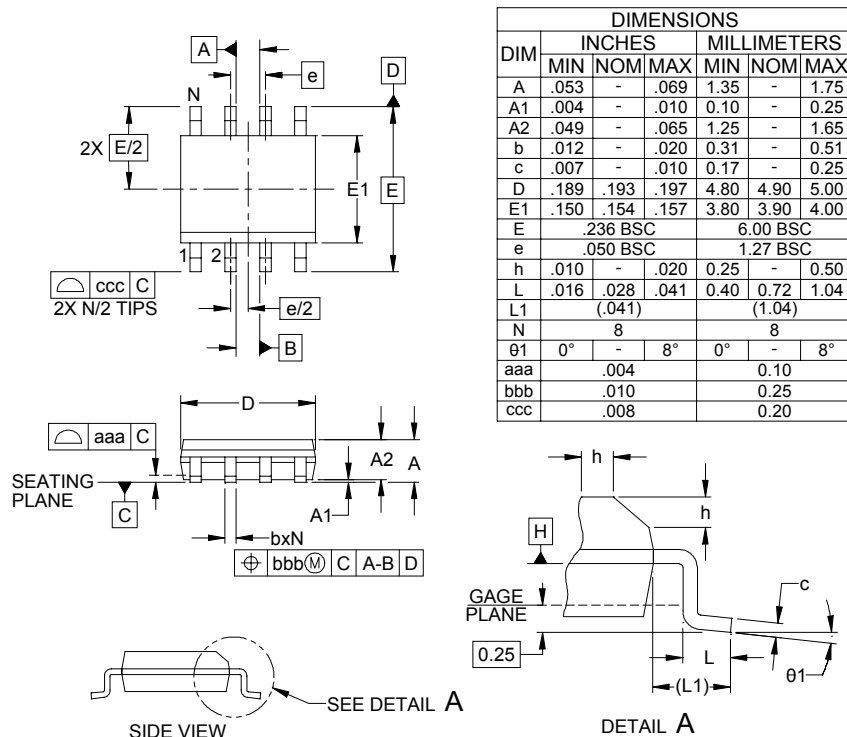
Typical Application Circuit (Cont.)

The schematic diagram illustrates a 3.3V to 25V step-up converter. The input is a 3.3V source connected to the non-inverting input of the SC1408CS (U1) via a 1N4148 diode (D4). The input is also filtered by a 100μF capacitor (C2). The SC1408CS is configured with its EN pin to the input, ISENSE pin to the feedback network, and REF pin to ground. The feedback network consists of a 10kΩ resistor (R4) and a 100μF capacitor (C3) in parallel, connected to the output. The output is also filtered by a 100μF capacitor (C8). The SC1408CS drives the gate of an IRL3103S MOSFET (Q1) through a 22μH inductor (L1). The MOSFET's source is connected to ground, and its drain is connected to the output via a 200kΩ resistor (R3). A 0.05Ω resistor (R2) is placed between the MOSFET's drain and the output. A 12V diode (D3) is connected in parallel with the input for protection. A 0.1μF capacitor (C4) is connected between the input and the EN pin. A 0.1μF capacitor (C5) is connected between the ISENSE pin and ground. A 470Ω resistor (R6) is connected between the input and the output. The output is labeled 25V OUT.

The schematic diagram illustrates a 3.3V to 12V boost converter. The input is a 3.3V IN terminal connected to a 5.1k resistor (R5) and a 100uF capacitor (C2). A J1 connector is used to control the device: pin 1 is connected to the EN pin (pin 4) and pin 2 is connected to the ISENSE pin (pin 5). The SC1408CS IC (U1) is configured with its BST pin (pin 2) to the input, GND pin (pin 7) to ground, and AGND pin (pin 6) to ground. The EN pin (pin 4) is connected to the ISENSE pin (pin 5). The REF pin (pin 5) is connected to the FB pin (pin 3). The GATE pin (pin 1) is connected to the gate of the MOSFET (Q1, IRL3303). The MOSFET's source is connected to ground, and its drain is connected to the inductor (L1, 22uH). The inductor's other end is connected to the diode (D1, B130T) and a 90k resistor (R3). The diode's cathode is connected to the MOSFET's drain. The output of the converter is taken from the node after the diode, passing through a 0.05Ohm resistor (R2) and a 10.0k resistor (R4) to a 100uF capacitor (C3). The final output is 12V OUT, which is also connected to a 100uF capacitor (C8). A legend indicates that a short on J1 results in RUN mode and an open results in SHUTDOWN mode.

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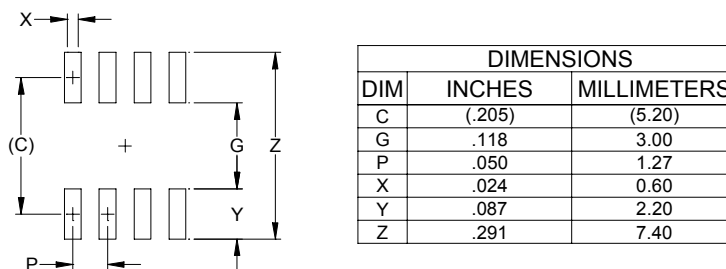
Outline Drawing - SO-8



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. DATUMS **-A-** AND **-B-** TO BE DETERMINED AT DATUM PLANE **-H-**
3. DIMENSIONS "E1" AND "D" DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
4. REFERENCE JEDEC STD MS-012, VARIATION AA.

Minimum Land Pattern - SO-8

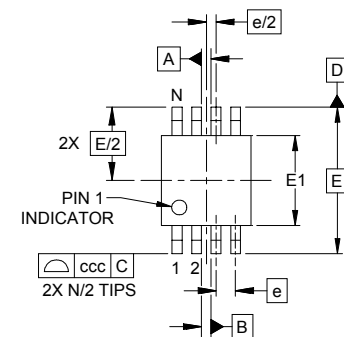


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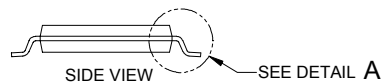
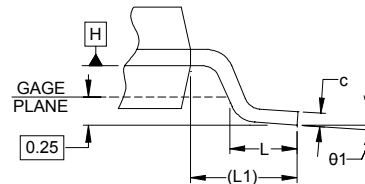
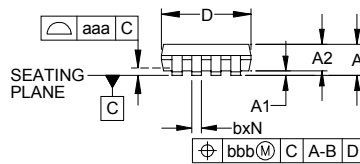
1. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.
2. REFERENCE IPC-SM-782A, RLP NO. 300A.

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Outline Drawing - MSOP-8



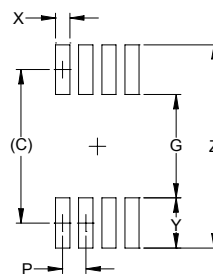
DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	-	.043	-	-	1.10
A1	.000	-	.006	0.00	-	0.15
A2	.030	-	.037	0.75	-	0.95
b	.009	-	.015	0.22	-	0.38
c	.003	-	.009	0.08	-	0.23
D	.114	.118	.122	2.90	3.00	3.10
E1	.114	.118	.122	2.90	3.00	3.10
E	.193 BSC			4.90 BSC		
e	.026 BSC			0.65 BSC		
L	.016	.024	.032	0.40	0.60	0.80
L1	(.037)			(.95)		
N	8			8		
θ1	0°	-	8°	0°	-	8°
aaa	.004			0.10		
bbb	.005			0.13		
ccc	.010			0.25		



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. DATUMS **-A-** AND **-B-** TO BE DETERMINED AT DATUM PLANE **-H-**.
3. DIMENSIONS "E1" AND "D" DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
4. REFERENCE JEDEC STD MO-187, VARIATION AA.

Land Pattern - MSOP-8



DIM	DIMENSIONS	
	INCHES	MILLIMETERS
C	(.161)	(4.10)
G	.098	2.50
P	.026	0.65
X	.016	0.40
Y	.063	1.60
Z	.224	5.70

NOTES:

1. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

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